



**ALPHA & OMEGA**  
SEMICONDUCTOR

# AOTF095A60L/AOT095A60L/AOB095A60L

600V,  $\alpha$  MOS5™ N-Channel Power Transistor

## General Description

- Proprietary  $\alpha$ MOS5™ technology
- Low  $R_{DS(ON)}$
- Optimized switching parameters for better EMI performance
- Enhanced body diode for robustness and fast reverse recovery

## Applications

- SMPS with PFC, Flyback and LLC topologies
- Micro inverter with DC/AC inverter topology

## Product Summary

$V_{DS}$ @ $T_{j,max}$	700V
$I_{DM}$	152A
$R_{DS(ON),max}$	< 0.095Ω
$Q_{g,typ}$	78nC
$E_{oss}$ @ 400V	7.8μJ

100% UIS Tested  
100%  $R_g$  Tested



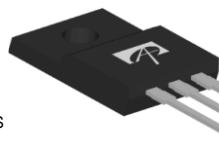
## Top View

TO-220



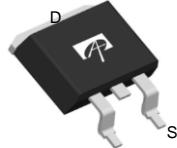
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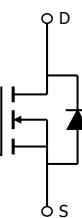


AOTF095A60L

TO-263  
D2PAK



AOB095A60L



## Orderable Part Number

## Package Type

## Form

## Minimum Order Quantity

AOTF095A60L	TO-220F Green	Tube	1000
AOT095A60L	TO-220 Green	Tube	1000
AOB095A60L	TO-263 Green	Tape&Reel	800

## Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	AOT(B)095A60L	AOTF095A60L	Units
Drain-Source Voltage	$V_{DS}$	600		V
Gate-Source Voltage	$V_{GS}$	$\pm 20$		V
Gate-Source Voltage (dynamic) AC ( $f>1\text{Hz}$ )	$V_{GS}$	$\pm 30$		V
Continuous Drain Current	$I_D$	38	38*	A
$T_C=100^\circ\text{C}$		24	24*	
Pulsed Drain Current <sup>C</sup>	$I_{DM}$	152		
Avalanche Current <sup>C</sup>	$I_{AR}$	11		A
Repetitive avalanche energy <sup>C</sup>	$E_{AR}$	60		mJ
Single pulsed avalanche energy <sup>G</sup>	$E_{AS}$	480		mJ
MOSFET dv/dt ruggedness	dv/dt	100		V/ns
Diode reverse recovery	dv/dt	20		V/ns
$V_{DS}=0$ to 400V, $I_F \leq 20\text{A}$ , $T_j=25^\circ\text{C}$	di/dt	500		A/us
$T_C=25^\circ\text{C}$	$P_D$	378	41	W
Power Dissipation <sup>B</sup>		3.0	0.3	W/ $^\circ\text{C}$
Junction and Storage Temperature Range	$T_J$ , $T_{STG}$	-55 to 150		$^\circ\text{C}$
Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds	$T_L$	300		$^\circ\text{C}$

## Thermal Characteristics

Parameter	Symbol	AOT(B)095A60L	AOTF095A60L	Units
Maximum Junction-to-Ambient <sup>A,D</sup>	$R_{\theta JA}$	65	65	$^\circ\text{C/W}$
Maximum Case-to-sink <sup>A</sup>	$R_{\theta CS}$	0.5	--	$^\circ\text{C/W}$
Maximum Junction-to-Case	$R_{\theta JC}$	0.33	3	$^\circ\text{C/W}$

\* Drain current limited by maximum junction temperature.

**Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>STATIC PARAMETERS</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}, V_{GS}=0\text{V}, T_J=25^\circ\text{C}$	600			V
		$I_D=250\mu\text{A}, V_{GS}=0\text{V}, T_J=150^\circ\text{C}$		700		
$BV_{DSS}/\Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$		0.51		$\text{V}/^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=600\text{V}, V_{GS}=0\text{V}$			1	$\mu\text{A}$
		$V_{DS}=480\text{V}, T_J=125^\circ\text{C}$			10	
$I_{GSS}$	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$			$\pm 100$	nA
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=5\text{V}, I_D=250\mu\text{A}$	2.4	3	3.6	V
$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}, I_D=19\text{A}$		0.082	0.095	$\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS}=10\text{V}, I_D=19\text{A}$		25		S
$V_{SD}$	Diode Forward Voltage	$I_S=19\text{A}, V_{GS}=0\text{V}$		0.86	1.2	V
$I_S$	Maximum Body-Diode Continuous Current				38	A
$I_{SM}$	Maximum Body-Diode Pulsed Current <sup>C</sup>				152	A
<b>DYNAMIC PARAMETERS</b>						
$C_{iss}$	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=100\text{V}, f=1\text{MHz}$		4010		pF
$C_{oss}$	Output Capacitance			105		pF
$C_{o(er)}$	Effective output capacitance, energy related <sup>H</sup>	$V_{GS}=0\text{V}, V_{DS}=0 \text{ to } 480\text{V}, f=1\text{MHz}$		90		pF
$C_{o(tr)}$	Effective output capacitance, time related <sup>I</sup>			390		pF
$C_{rss}$	Reverse Transfer Capacitance	$V_{GS}=0\text{V}, V_{DS}=100\text{V}, f=1\text{MHz}$		1.2		pF
$R_g$	Gate resistance	$f=1\text{MHz}$		5.5		$\Omega$
<b>SWITCHING PARAMETERS</b>						
$Q_g$	Total Gate Charge	$V_{GS}=10\text{V}, V_{DS}=480\text{V}, I_D=19\text{A}$		78		nC
$Q_{gs}$	Gate Source Charge			28		nC
$Q_{gd}$	Gate Drain Charge			24		nC
$t_{D(on)}$	Turn-On DelayTime	$V_{GS}=10\text{V}, V_{DS}=400\text{V}, I_D=19\text{A}, R_G=5\Omega$		48		ns
$t_r$	Turn-On Rise Time			50		ns
$t_{D(off)}$	Turn-Off DelayTime			99		ns
$t_f$	Turn-Off Fall Time			33		ns
$t_{rr}$	Body Diode Reverse Recovery Time	$I_F=19\text{A}, dI/dt=100\text{A}/\mu\text{s}, V_{DS}=400\text{V}$		444		ns
$I_{rm}$	Peak Reverse Recovery Current			36		A
$Q_{rr}$	Body Diode Reverse Recovery Charge			11.5		$\mu\text{C}$

A. The value of  $R_{\text{aja}}$  is measured with the device in a still air environment with  $T_A=25^\circ\text{C}$ .

B. The power dissipation  $P_0$  is based on  $T_{J(\text{MAX})}=150^\circ\text{C}$ , using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C. Repetitive rating, pulse width limited by junction temperature  $T_{J(\text{MAX})}=150^\circ\text{C}$ . Ratings are based on low frequency and duty cycles to keep initial  $T_J=25^\circ\text{C}$ .

D. The  $R_{\text{aja}}$  is the sum of the thermal impedance from junction to case  $R_{\text{jJC}}$  and case to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using  $<300\mu\text{s}$  pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink  $k$ , assuming a maximum junction temperature of  $T_{J(\text{MAX})}=150^\circ\text{C}$ . The SOA curve provides a single pulse rating.

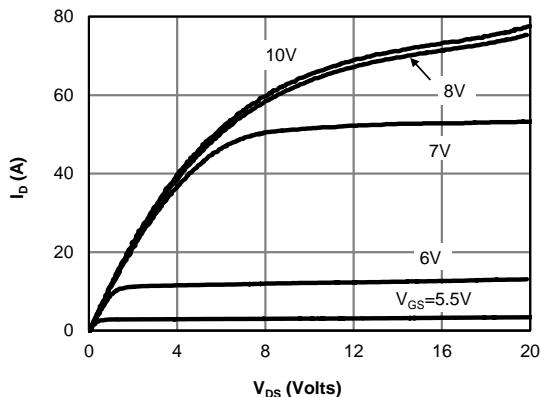
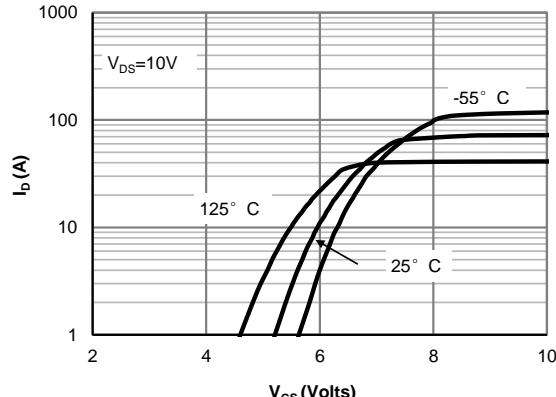
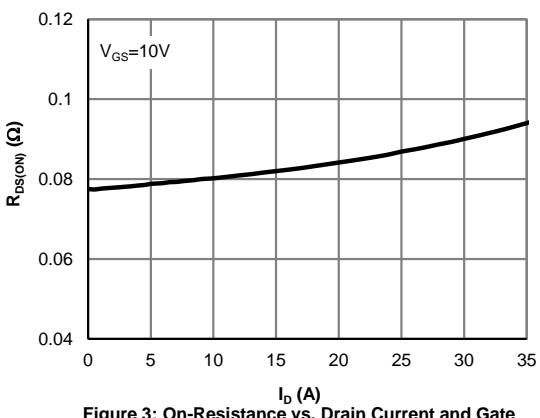
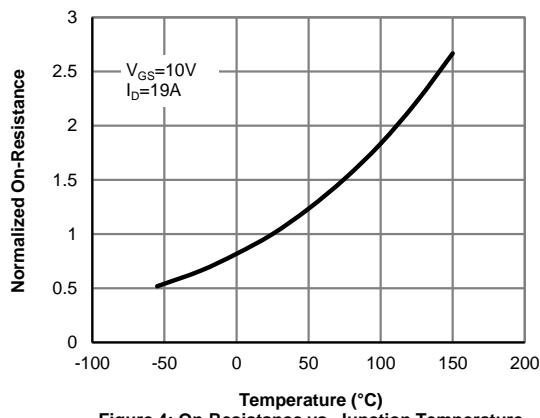
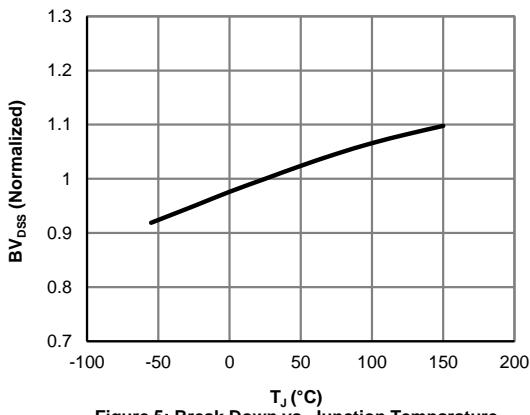
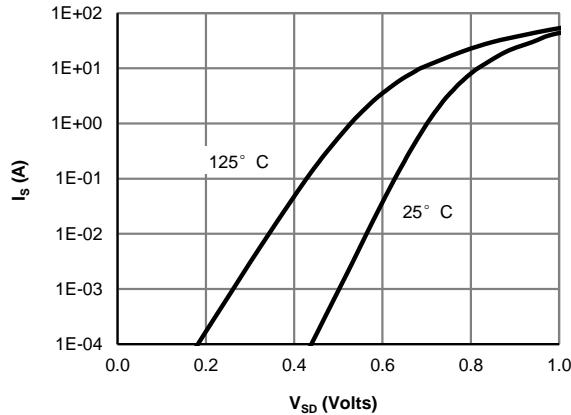
G.  $L=60\text{mH}, I_{AS}=4\text{ A}, R_G=25\Omega$ , Starting  $T_J=25^\circ\text{C}$ .

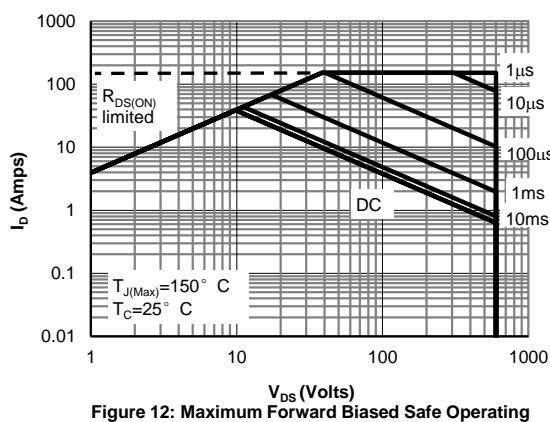
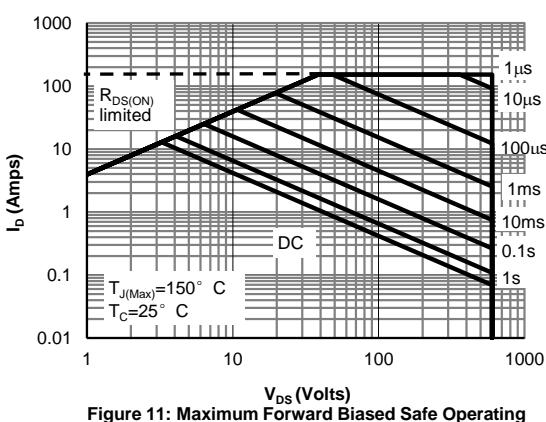
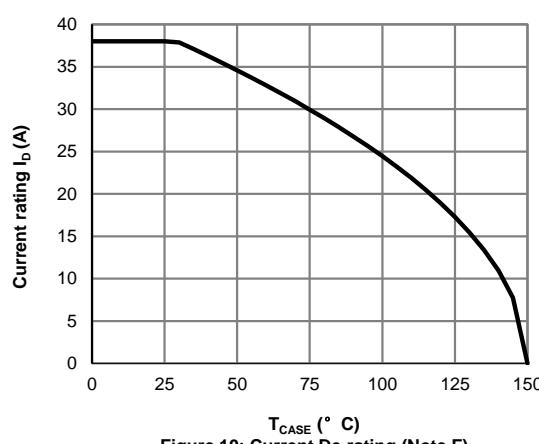
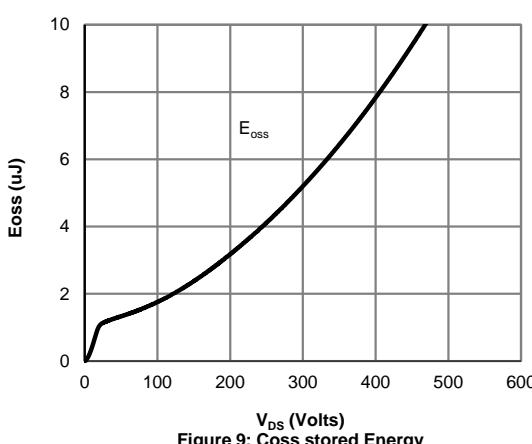
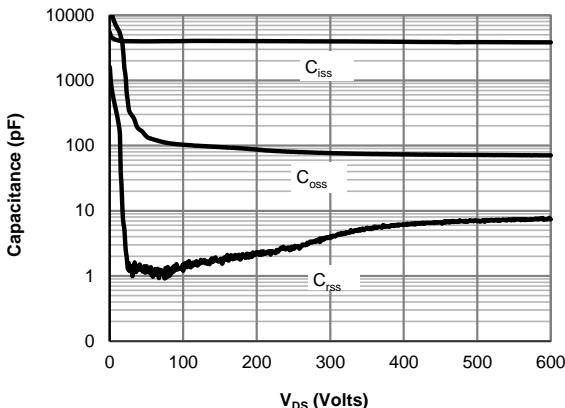
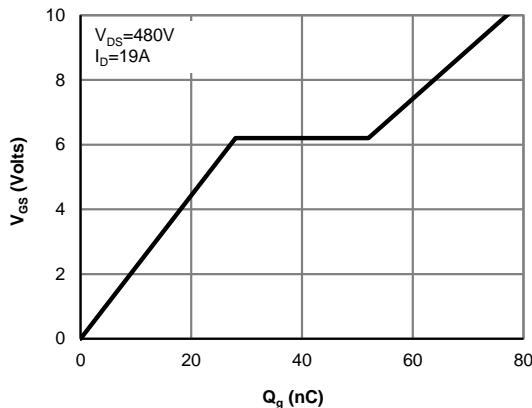
H.  $C_{o(er)}$  is a fixed capacitance that gives the same stored energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 to 80%  $V_{(BR)DSS}$ .

I.  $C_{o(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 to 80%  $V_{(BR)DSS}$ .

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**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**

**Figure 1: On-Region Characteristics**

**Figure 2: Transfer Characteristics**

**Figure 3: On-Resistance vs. Drain Current and Gate Voltage**

**Figure 4: On-Resistance vs. Junction Temperature**

**Figure 5: Break Down vs. Junction Temperature**

**Figure 6: Body-Diode Characteristics**

**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**


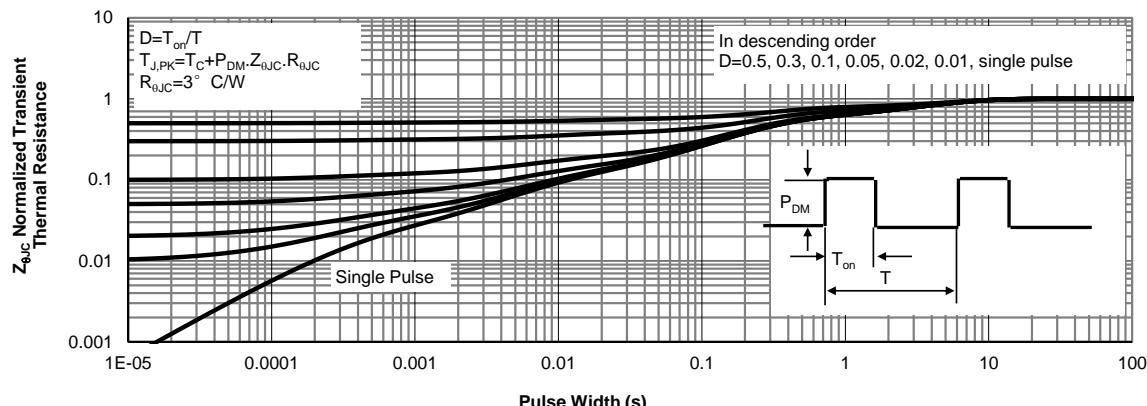
**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**


Figure 13: Normalized Maximum Transient Thermal Impedance for AOTF095A60L (Note F)

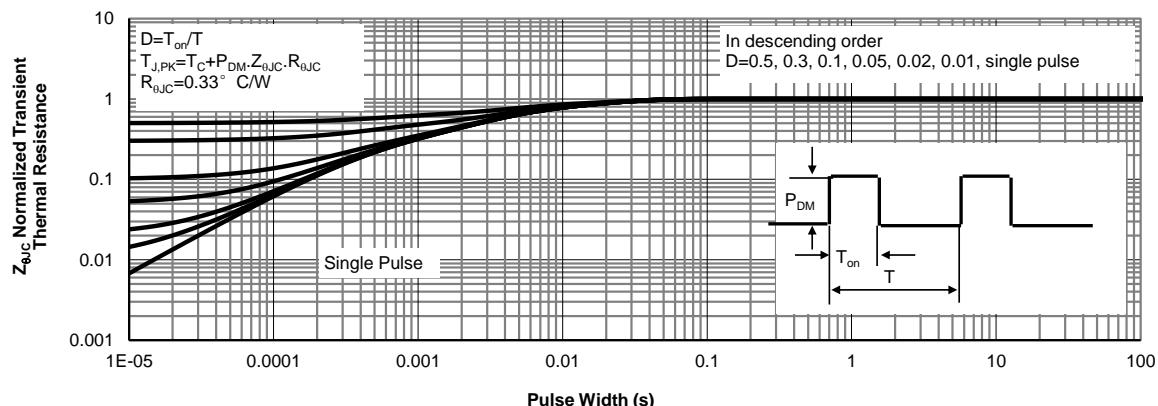
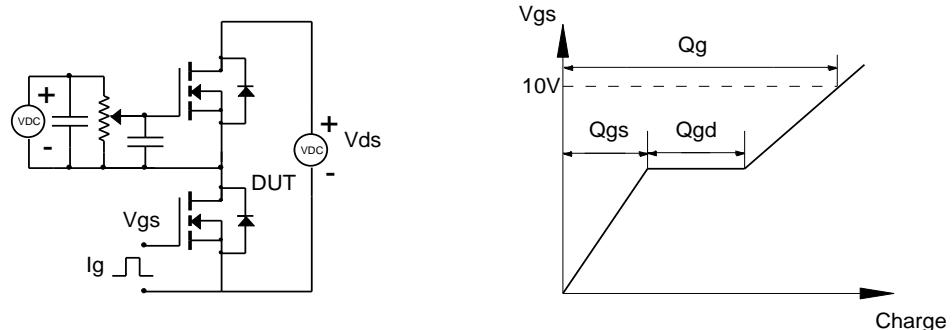
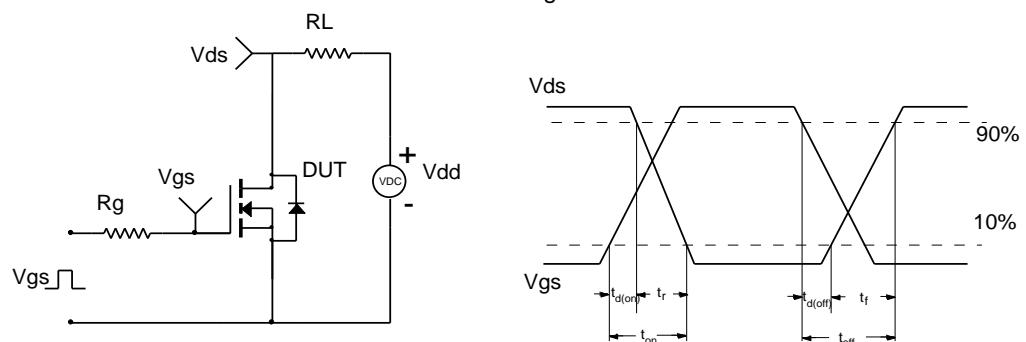
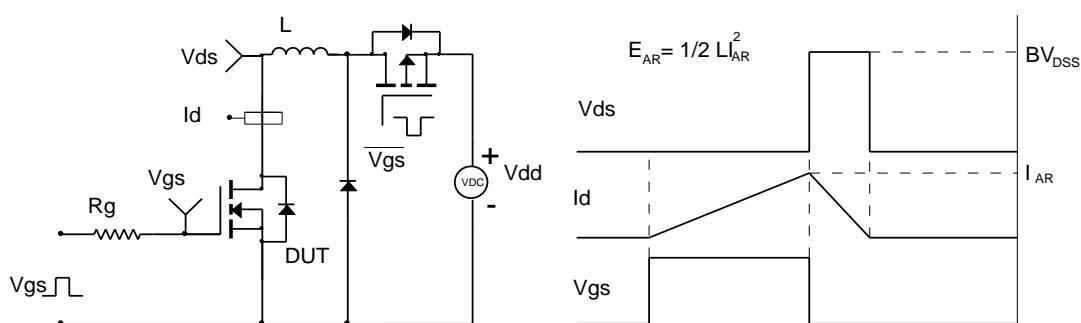


Figure 14: Normalized Maximum Transient Thermal Impedance for AOT(B)095A60L (Note F)

**Gate Charge Test Circuit & Waveform**

**Resistive Switching Test Circuit & Waveforms**

**Unclamped Inductive Switching (UIS) Test Circuit & Waveforms**

**Diode Recovery Test Circuit & Waveforms**
